

ID	R <sub>Ds(ON)</sub> (Typ)	V <sub>DSS</sub>
20A	160mΩ	650V

**Applications:**

- Switch Mode Power Supply(SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC)
- AC-DC Switching Power Supply

**Features:**

- Fast switching speed
- 100% avalanche tested
- Improved dv/dt capability

**Ordering Information**

Part Number	Package	Marking	Packing	Qty.
RS65R190F	T0-220F	RS65R190F	Tube	50 PCS

**Absolute Maximum Ratings T<sub>c</sub>= 25°C unless otherwise specified**

Symbol	Parameter	RS65R190F	Units
VDSS	Drain-to-Source Voltage	650	V
ID	Continuous Drain Current TC=25°C	20	A
ID	Continuous Drain Current TC=100°C	13	
IDM	Pulsed Drain Current (Note*1)	60	
PD	Power Dissipation	34	W
VGS	Gate- to- Source Voltage	±30	V
EAS	Single Pulse Avalanche Energy L=10mH, VDS= 50V, RG = 25 Ω, TC=25°C	310	mJ
dv/dt	MOSFET dv/ dt ruggedness VDS = 0...400V	50	V/ns
dv/dt	Reverse diode dv/dt VDS = 0...400V, T <sub>j</sub> = 25°C, ISD≤ID	15	V/ns
TL TPKG	Maximum Temperature for Soldering	300 260	°C
	Leads at 0.063in(1.6mm)from Case for 10 seconds Package Body for 10 seconds		
TJ and TSTG	Operating Junction and Storage Temperature Range	-55 to 150	

\* Drain Current Limited by Maximum Junction Temperature

Caution: Stresses greater than those listed in the "Absolute Maximum Ratings" Table may cause permanent damage to the device.

**Thermal Resistance**

Symbol	Parameter	RS65R190F	Units	Test Conditions
R <sub>θJC</sub>	Junction-to-Case	3.7	°C / W	Drain lead soldered to water cooled heatsink, PD adjusted for a peak junction temperature of + 150 °C
R <sub>θJA</sub>	Junction-to-Ambient	80		1 cubic foot chamber, free air.

**OFF Characteristics** TJ= 25°C unless otherwise specified

Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
BVDSS	Drain- to- source Breakdown Voltage	650	--	--	V	VGS=0V, ID=250μA
IDSS	Drain- to- Source Leakage Current	--	--	1	μA	VDS=650V, VGS=0V
IGSS	Gate- to- Source Forward Leakage	--	--	100	nA	VGS=30V, VDS=0V
	Gate- to- Source Reverse Leakage	--	--	-100		VGS=-30V, VDS=0V

**ON Characteristics** TJ=25°C unless otherwise specified

Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
RDS(on)	Static Drain- to- Source On-Resistance (Note*2)	--	160	190	mΩ	VGS=10V, ID=10A
VGS(TH)	Gate Threshold Voltage	2	--	4	V	VGS=VDS, ID=250μA

**Resistive Switching Characteristics** Essentially independent of operating temperature

Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
td(ON)	Turn- on Delay Time	--	23	--	nS	VDS=325V ID=20A RG=25Ω
trise	Rise Time	--	35	--		
td(OFF)	Turn- OFF Delay Time	--	113	--		
tfall	Fall Time	--	28	--		

**Dynamic Characteristics** Essentially independent of operating temperature

Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
Ciss	Input Capacitance	--	1490	--	pF	VGS=0V VDS=50V f=1.0MHz
Coss	Output Capacitance	--	101	--		
Crss	Reverse Transfer Capacitance	--	2.3	--		
Qg	Total Gate Charge	--	36	--	nC	VDS=520V ID=20A VGS=10V
Qgs	Gate- to- Source Charge	--	7.2	--		
Qgd	Gate-to-Drain(" Miller") Charge	--	16	--		

**Source- Drain Diode Characteristics**

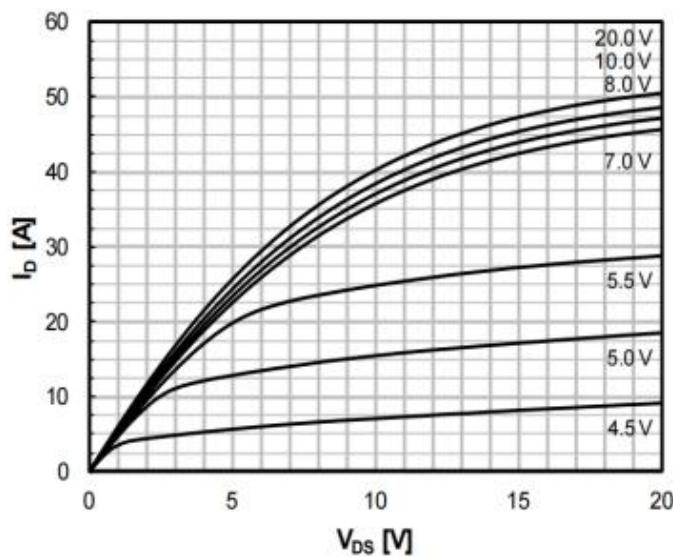
Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
IS	Continuous Source Current	--	--	20	A	Integral pn- diode in MOSFET
ISM	Maximum Pulsed Current	--	--	60	A	
VSD	Diode Forward Voltage	--	--	1.4	V	IS=20A,VGS=0V
trr	Reverse Recovery Time	--	347	--	nS	VR=100V IS=20A,di/dt=100A /μs
Qrr	Reverse Recovery Charge	--	5	--	μC	

**Notes:**

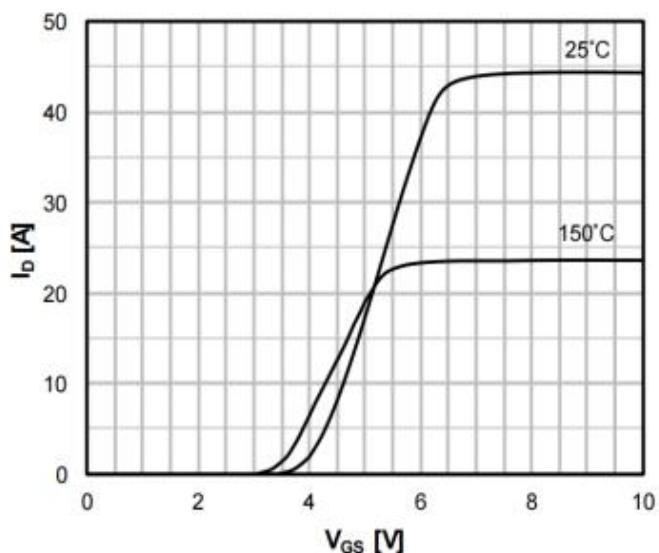
- \* 1. Repetitive rating, pulse width limited by maximum junction temperature.
- \* 2. Pulse Test: Pulse width ≤ 300μs, Duty Cycle ≤ 2%

### Typical Feature Curve

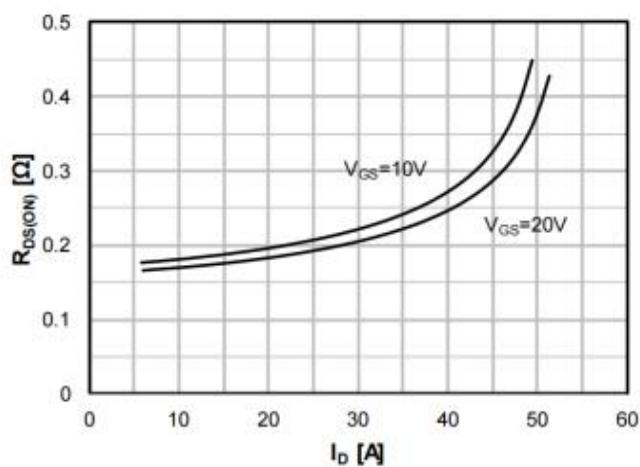
**Figure1. Output Characteristics**



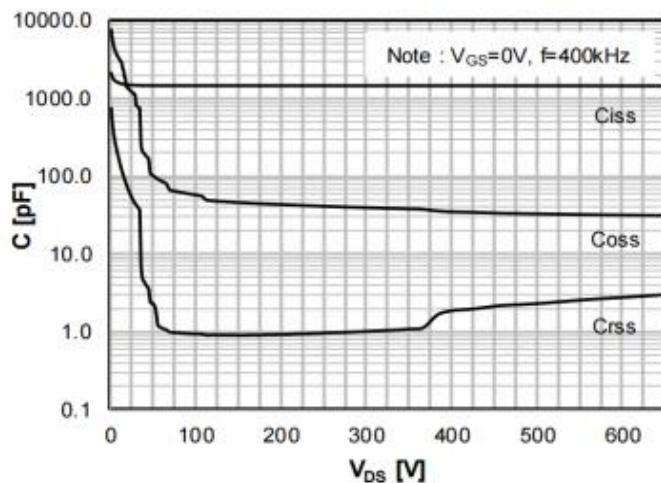
**Figure2. Transfer Characteristics**



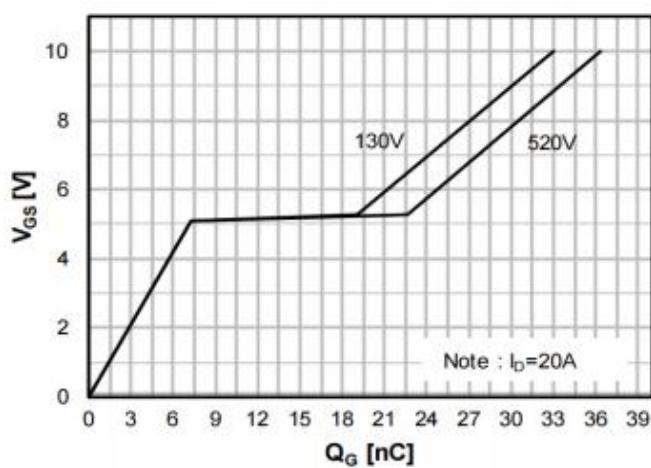
**Figure 3. On-Resistance VS.Drain Current**



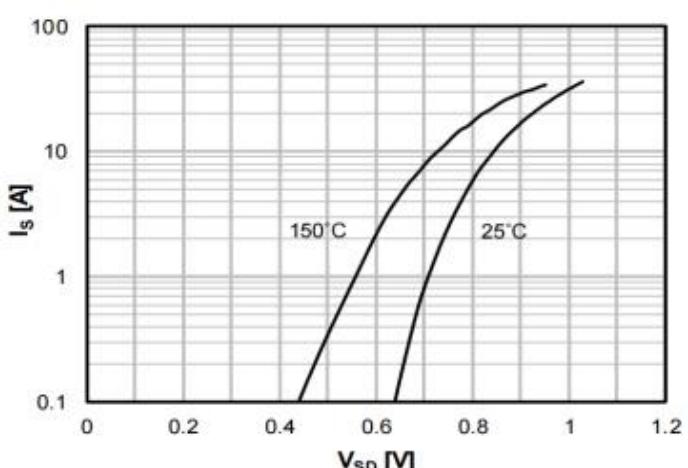
**Figure 4. Capacitance**



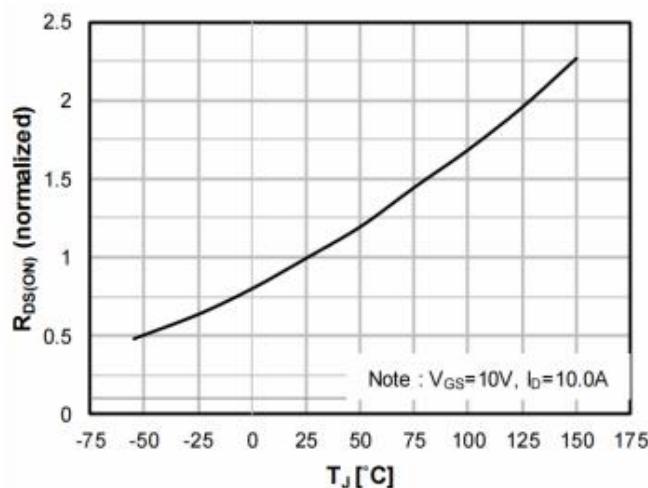
**Figure 5. Gate Charge**



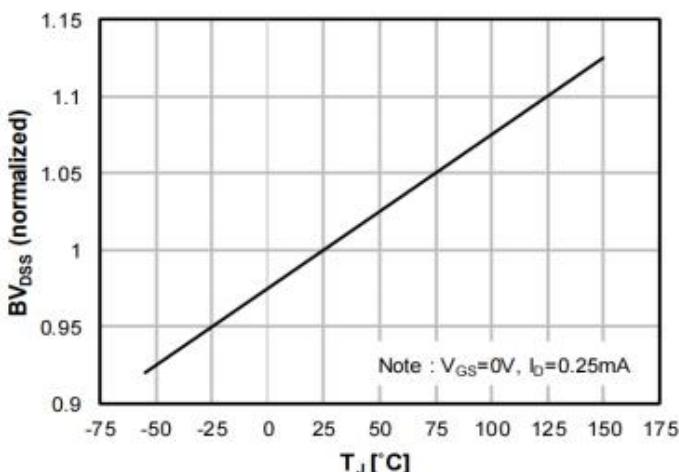
**Figure 6. Body Diode Forward Voltage**



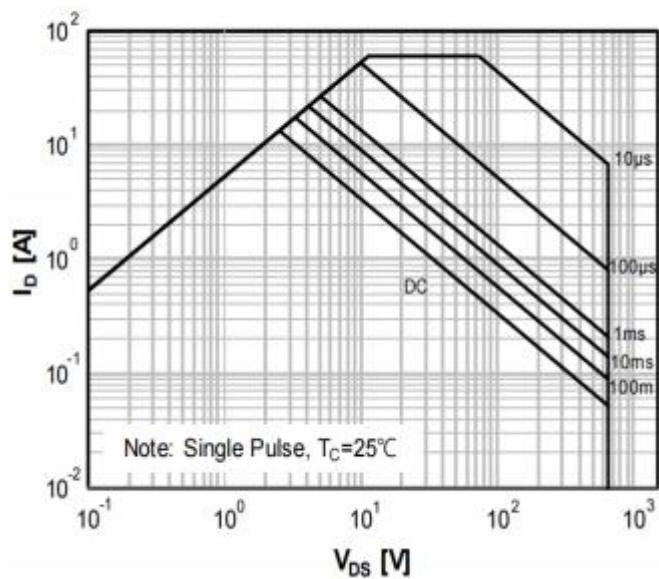
**Figure 7.On-Resistance vs.  
Junction Temperature**



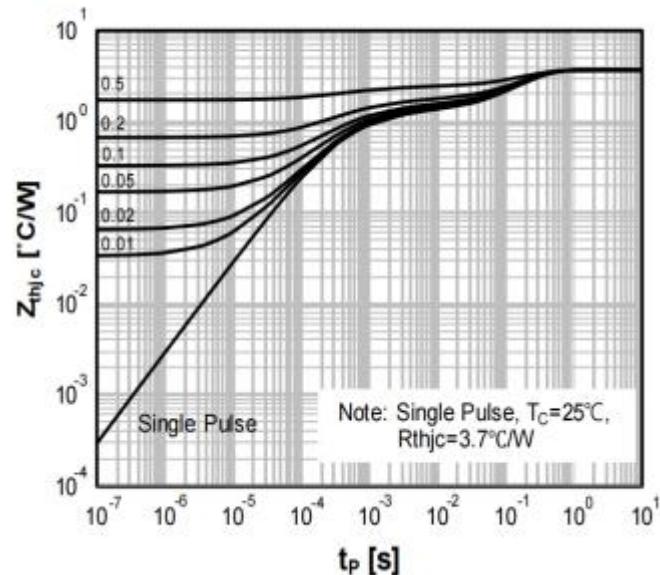
**Figure 8.Breakdown Voltage vs.  
Junction Temperature**



**Figure 9.Safe operation area**



**Figure 10.Transient Thermal Impedance**



## Test Circuits and Waveforms

Figure A: Gate Charge Test Circuit and Waveform

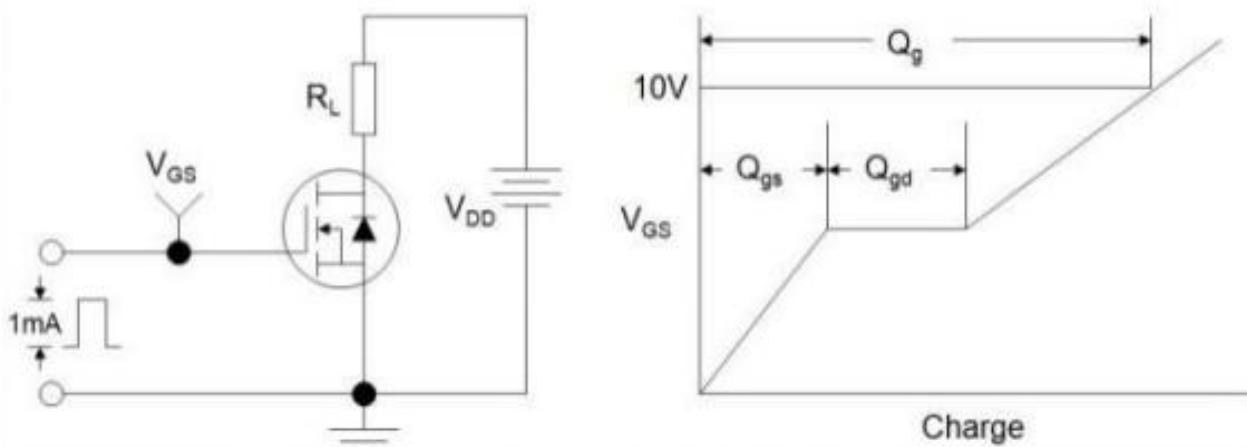


Figure B: Resistive Switching Test Circuit and Waveform

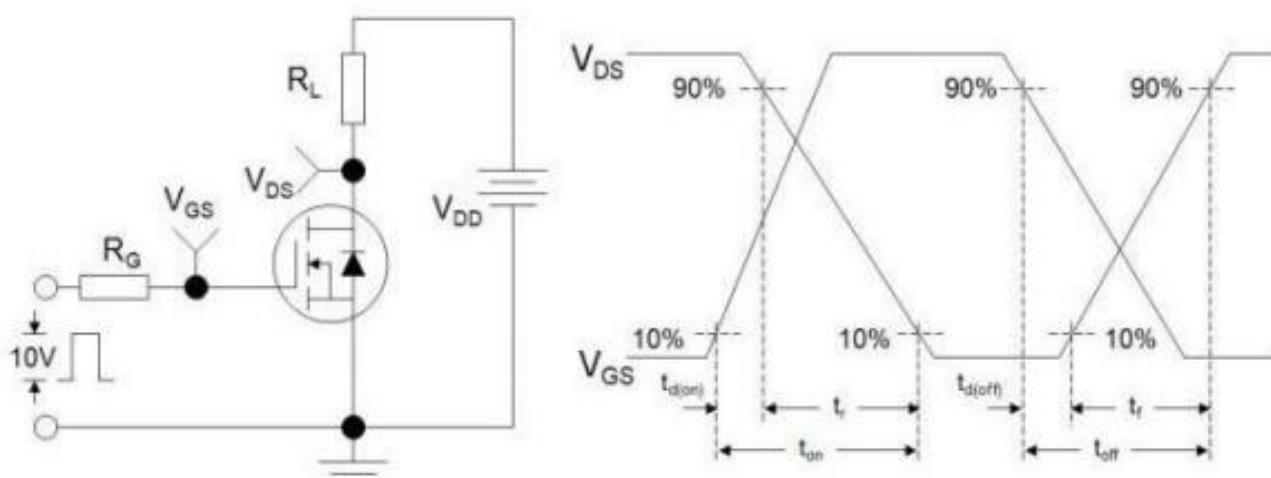
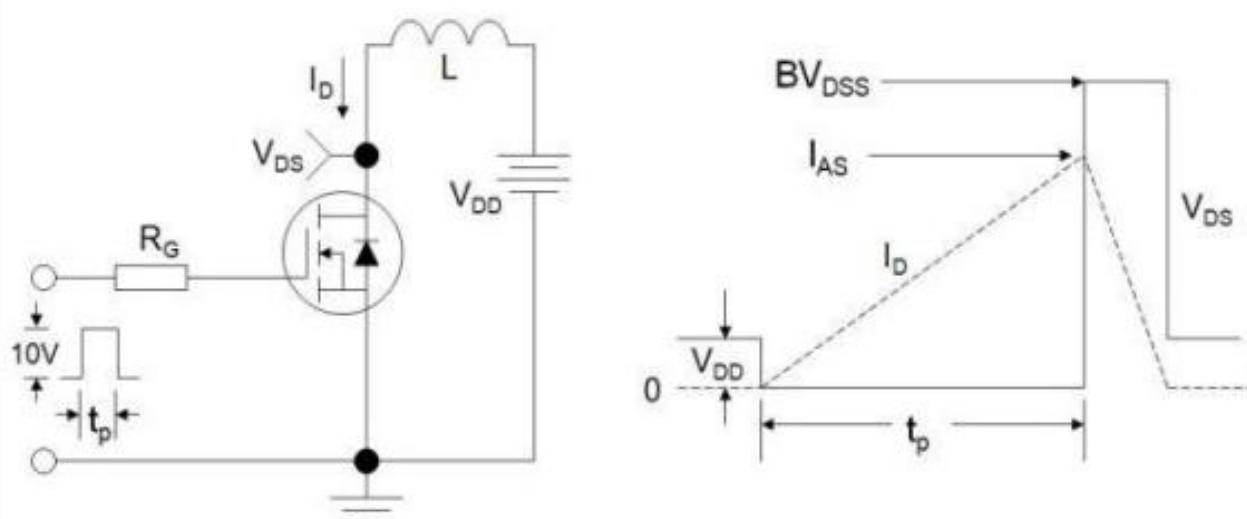
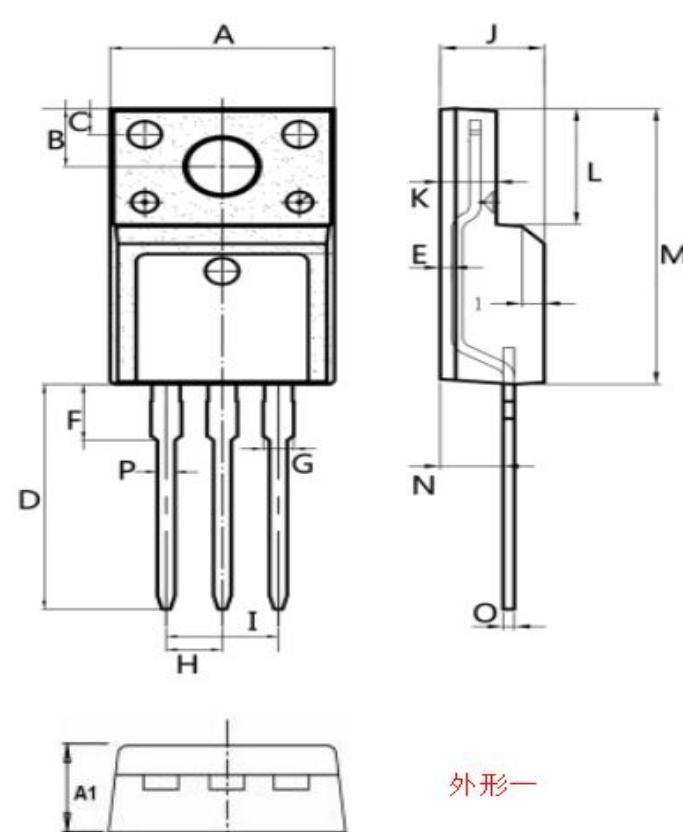


Figure C: Unclamped Inductive Switching Test Circuit and Waveform

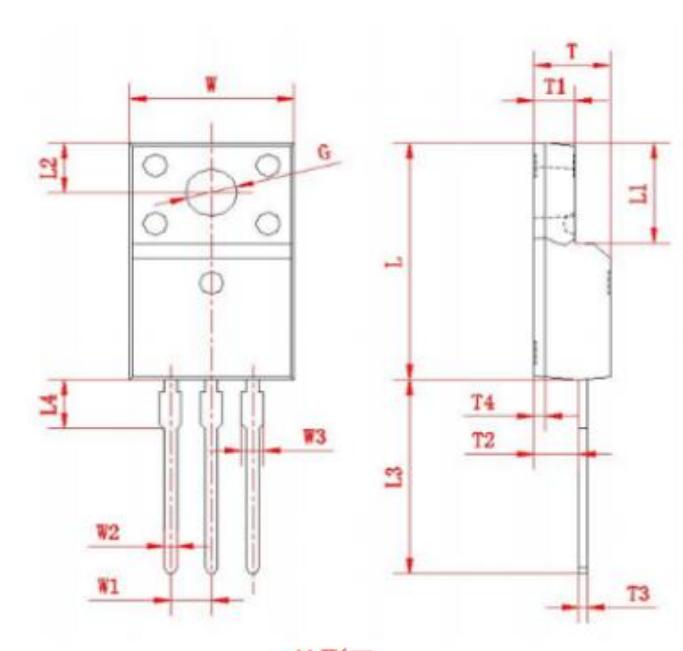


**Package outline drawing(TO-220F Unit: mm)**


外形一

Dim.	Min.	Max.
A	9.95	10.36
A1	4.5	5.0
B	2.95	3.25
C	1.25	1.45
D	12.60	13.60
E	0.40	0.60
F	2.8	3.5
G	1.30	1.45
H	(2.54)	
I	(5.08)	
J	4.60	4.75
K	2.45	2.65
L	6.5	6.8
M	15.4	16.0
N	2.25	3.05
O	0.45	0.55
P	0.70	0.90

All Dimensions in millimeter



外形二

Dim.	Min.	Max.
W	9.95	10.36
W1	(2.54)	
W2	0.70	0.90
W3	1.25	1.47
L	15.67	16.07
L1	6.48	6.88
L2	3.2	3.4
L3	12.6	13.6
L4	(3.23)	
T	4.50	4.90
T1	2.34	2.74
T2	2.25	2.95
T3	0.45	0.60
T4	(0.70)	
G	3.08	3.28

All Dimensions in millimeter

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